

### General Description

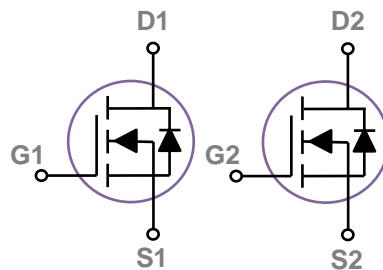
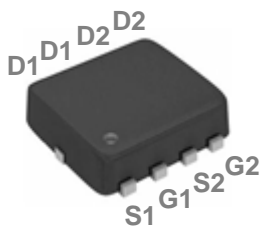
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
100V	350mΩ	5.1A

### Features

- 100V, 5.1A,  $R_{DS(ON)} = 350m\Omega @ V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### PPAK3X3 Dual Pin Configuration



### Applications

- Networking
- Load switch
- LED applications

### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	1.6	A
	Drain Current – Continuous ( $T_A=70^\circ\text{C}$ )	1.28	A
	Drain Current – Continuous ( $T_C=25^\circ\text{C}$ )	5.1	A
	Drain Current – Continuous ( $T_C=100^\circ\text{C}$ )	3.2	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	20.4	A
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	2.01	W
	Power Dissipation ( $T_C=25^\circ\text{C}$ )	20.1	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.16	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	6.2	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.09	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	μA
		V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	---	290	350	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A	---	300	360	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	1.2	1.8	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =1A	---	2.3	---	S

**Dynamic Characteristics**

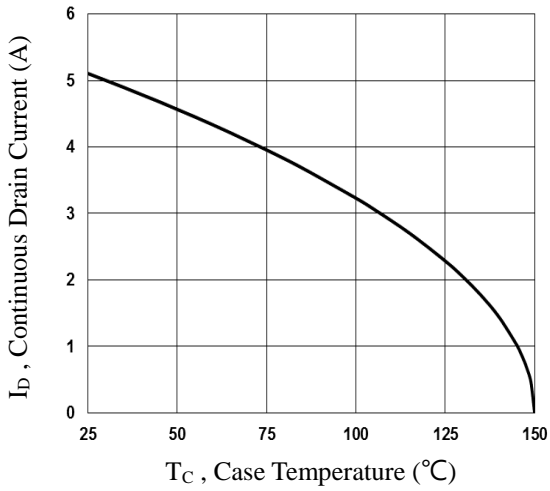
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =1A	---	9	18	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	2.3	4.6	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	1.1	2.5	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =50V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω I <sub>D</sub> =1A	---	5.2	10	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	6.8	12	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	14.5	28	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	2.1	5	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, F=1MHz	---	492	800	pF
C <sub>oss</sub>	Output Capacitance		---	27	50	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	15	25	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	2.8	5.6	Ω

**Drain-Source Diode Characteristics**

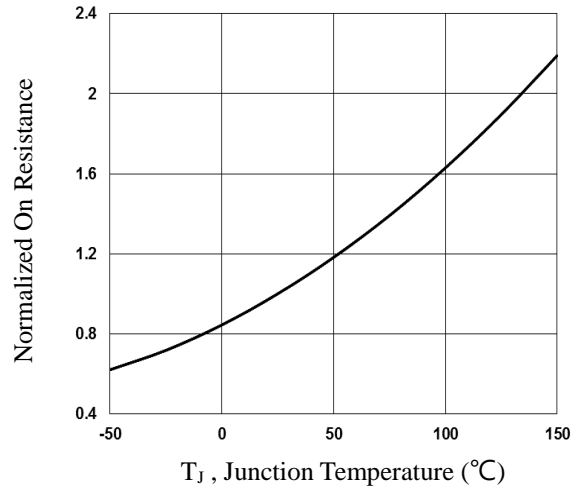
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	5.1	A
I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>		---	---	10.2	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

Note :

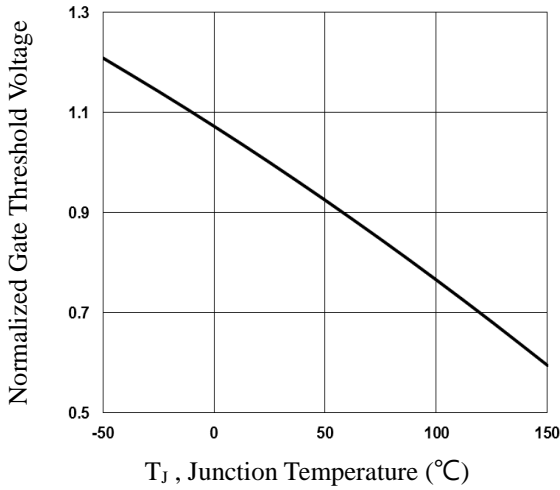
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



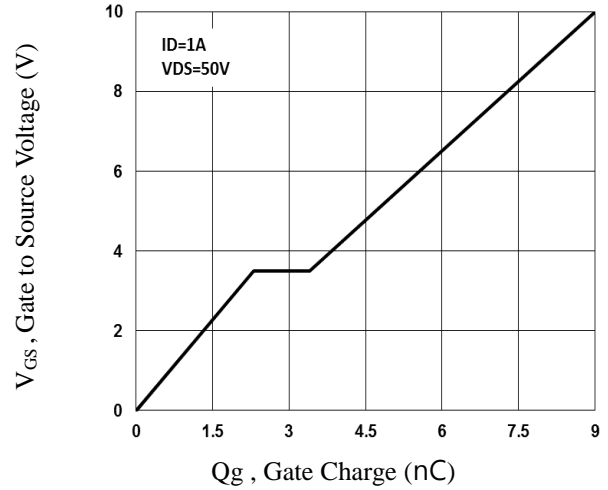
**Fig.1 Continuous Drain Current vs.  $T_c$**



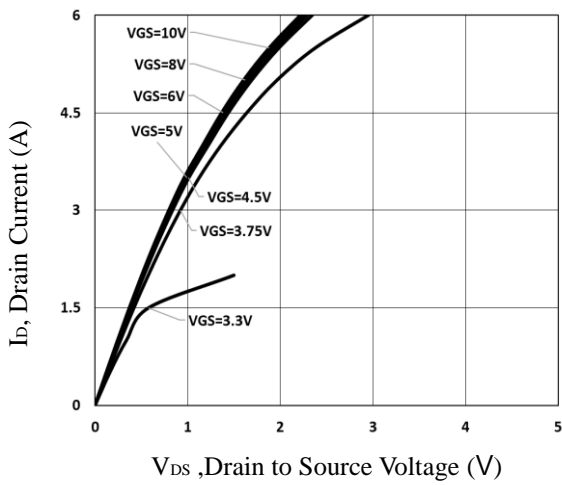
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



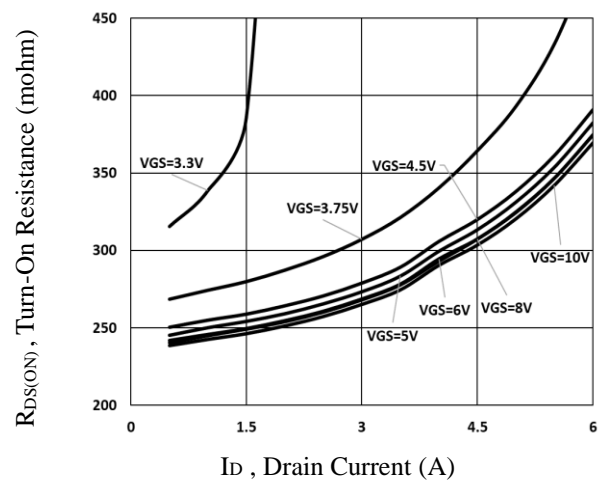
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



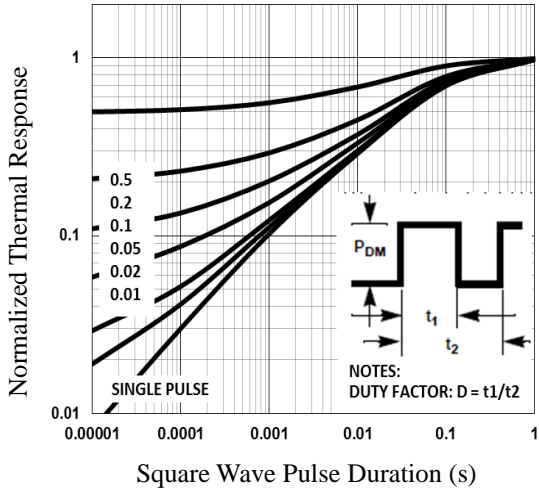
**Fig.4 Gate Charge Waveform**



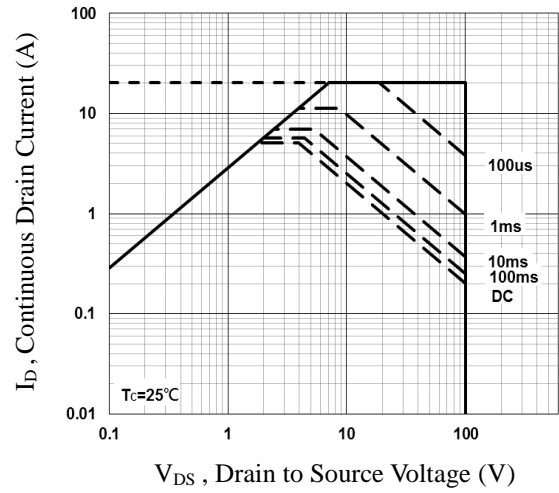
**Fig.5 Typical Output Characteristics**



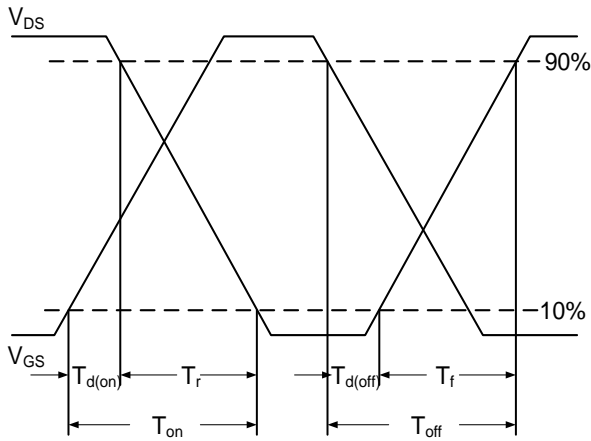
**Fig.6 Turn-On Resistance vs.  $I_D$**



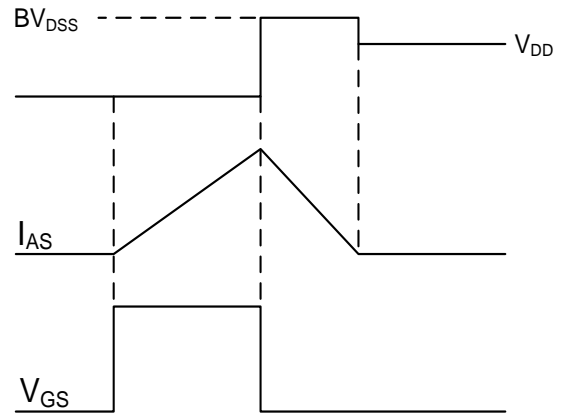
**Fig.7 Normalized Transient Impedance**



**Fig.8 Maximum Safe Operation Area**

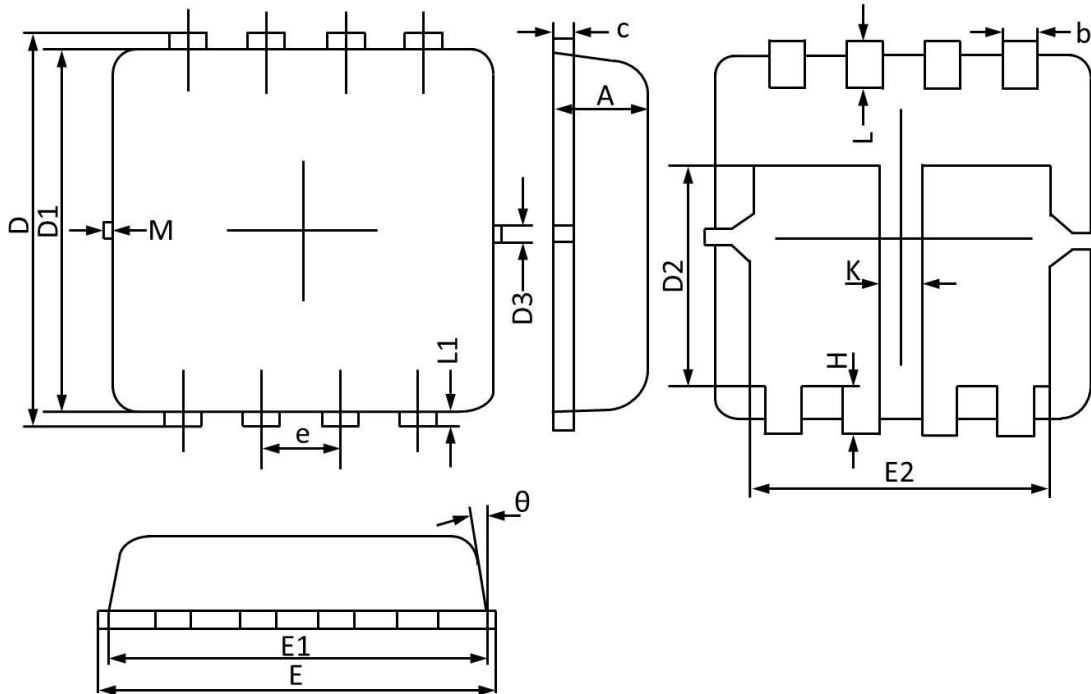


**Fig.9 Switching Time Waveform**



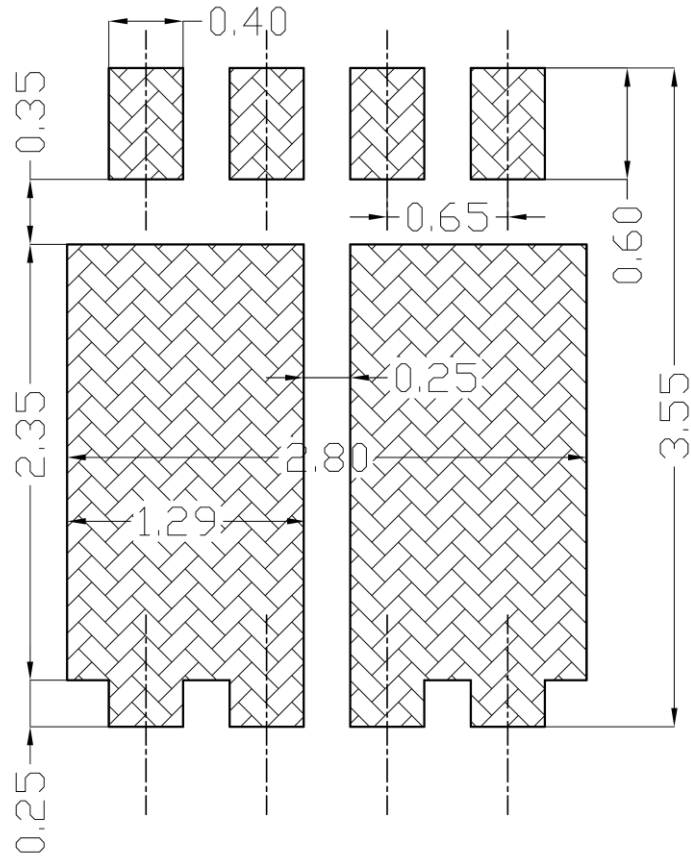
**Fig.10 EAS Waveform**

### PPAK3x3 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.670	0.880	0.026	0.035
b	0.250	0.350	0.010	0.014
c	0.100	0.250	0.004	0.010
D	3.150	3.550	0.124	0.140
D1	3.000	3.300	0.118	0.130
D2	1.500	2.000	0.059	0.079
D3	0.130	0.200	0.005	0.008
E	3.100	3.500	0.122	0.138
E1	3.000	3.200	0.118	0.126
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.012	0.020
L	0.300	0.500	0.012	0.020
L1	0.130 REF		0.005 REF	
K	0.300 REF		0.012 REF	
theta	0°	12°	0°	12°
M	0.150 REF		0.006 REF	

PPAK3X3 Dual RECOMMENDED LAND PATTERN



unit : mm